

INTERCONNECTS

SERIES 850, 851, 852, 853 • .050" GRID HEADERS AND SOCKETS • SINGLE AND DOUBLE ROW STRIPS

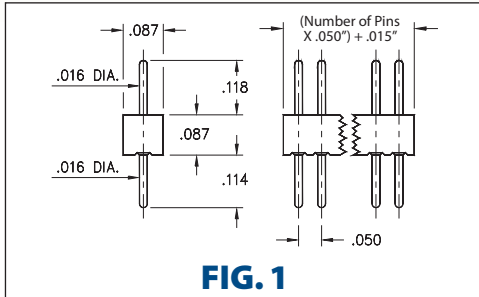


FIG. 1



FIG. 2

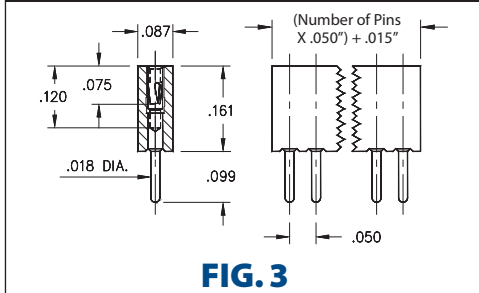


FIG. 3

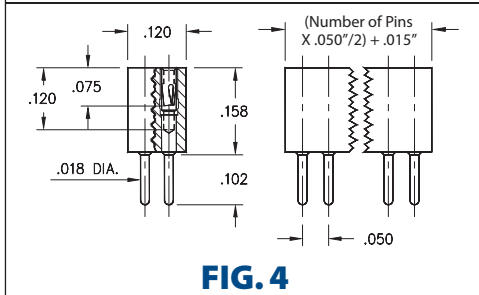


FIG. 4

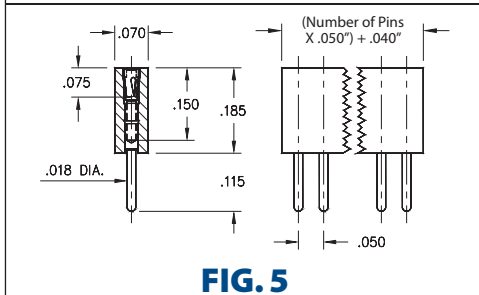
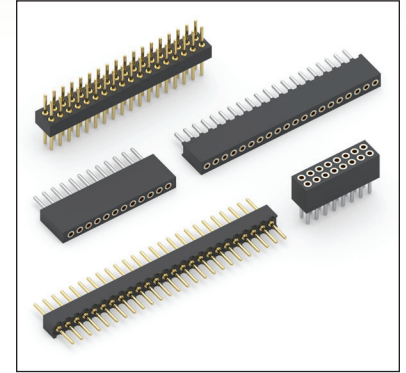


FIG. 5

- Series 850, 851, 852, 853 single and double row interconnects have .050" pin spacing and permit board stacking as low as .248"
- Pin headers have .016" dia. pins (MM #4006-0) See page 208 for details
- MM #0467 and MM #4890 receptacles use Hi-Rel, 3-finger BeCu #11 contact rated at 3 amps. (#11 contact accepts pin diameters from .015"-.020"). See pages 158 and 160 for details
- Insulators are high temperature thermoplastic, suitable for all soldering operations



ORDERING INFORMATION

FIG. 1	Series 850...001 Single Row .087" Profile Pin Header	
	850-XX-0-10-001000 Specify number of pins 01-50	
FIG. 2	Series 852...001 Double Row .083" Profile Pin Header	
	852-XX--10-001000 Specify number of pins 004-100	
RoHS-2 2011/65/EU XX=Plating Code See Below For Electrical, Mechanical & Environmental Data, See page 264		
SPECIFY PLATING CODE XX= 10 90 40		
Pin Plating 10 μ" Au 200 μ" Sn/Pb 200 μ" Sn		

FIG. 3	Series 851...001 Single Row .161" Profile Socket	
	851-XX-0-10-001000 Specify number of pins 01-50	
FIG. 4	Series 853...001 Double Row .161" Profile Socket	
	853-XX--10-001000 Specify number of pins 004-100	
FIG. 5	Series 851...002 Single Row .185" Profile Socket	
	851-XX-0-10-002000 Specify number of pins 01-77	
RoHS-2 2011/65/EU XX=Plating Code See Below For Electrical, Mechanical & Environmental Data, See page 264		
SPECIFY PLATING CODE XX= 91 93 99 41 43 47		
Sleeve (Pin) 200 μ" Sn/Pb 200 μ" Sn/Pb 200 μ" Sn/Pb 200 μ" Sn 200 μ" Sn 200 μ" Sn		
Contact (Clip) 10 μ" Au 30 μ" Au 100 μ" Sn/Pb 10 μ" Au 30 μ" Au Au Flash		